

DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
201/	40mΩ @ V _{GS} = 4.5V	5.0A
30V	75mΩ @ V _{GS} = 2.5V	3.6A

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN3055LFDBQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Description and Applications

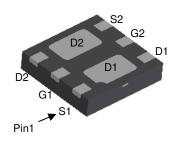
This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

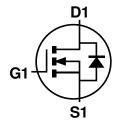
- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors

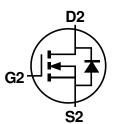
Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (Approximate)

U-DFN2020-6 (Type B)







Ordering Information (Note 4)

Part Number	Case	Packaging		
DMN3055LFDBQ-7	U-DFN2020-6 (Type B)	3,000/Tape & Reel		
DMN3055LFDBQ-13	U-DFN2020-6 (Type B)	10,000/Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information



M6 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 1 = 2021) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	0	1	2	3	4	5	6	7	8	9	0	1

	Week	1-26	27-52	53
ĺ	Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	Χ	Υ	Z



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage			VDSS	30	V
Gate-Source Voltage			V_{GSS}	±12	V
Continuous Drain Current (Note 6) $V_{GS} = 4.5V$ Steady $T_{A} = +25^{\circ}C$ State $T_{A} = +70^{\circ}C$			lo	5.0 4.0	Α
Maximum Continuous Body Diode Forward Curre	Is	1.5	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1	IDM	25	Α		
Avalanche Current (Note 7) L = 0.1mH			las	11	Α
Avalanche Energy (Note 7) L = 0.1mH			Eas	6	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)	T _A = +25°C	D-	0.81	W	
Total Fower Dissipation (Note 5)	T _A = +70°C	P _D	0.52	۷V	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	132	°C/W	
Thermal Resistance, sunction to Ambient (Note 3)	t<10s	RθJA	101		
Total Power Dissipation (Note 6)	T _A = +25°C	Pp	1.36	W	
Total Fower Dissipation (Note o)	T _A = +70°C	Fυ	0.87	V V	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	83	°C/W	
Themai Resistance, Junction to Ambient (Note 6)	t<10s	⊓⊎JA	60		
Thermal Resistance, Junction to Case (Note 6)	ReJC	10			
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, TJ = +25°C	IDSS	_	_	1.0	μA	$V_{DS} = 30V$, $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 12V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	1.5	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	0	_	32	40	mΩ	$V_{GS} = 4.5V, I_{D} = 3A$	
Static Dialii-Source Off-Nesistance	R _{DS(ON)}	_	52	75	11122	$V_{GS} = 2.5V, I_{D} = 2A$	
Diode Forward Voltage	V _{SD}	_	8.0	1.2	V	$V_{GS} = 0V$, $I_{S} = 2A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	1	458		рF	\	
Output Capacitance	Coss	-	50		рF	V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	44	_	pF	1 = 1.0WI IZ	
Gate Resistance	Rg	-	2.1		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Qg	_	11.2	_	nC		
Total Gate Charge (VGS = 4.5V)	Qg	-	5.3		nC	\/ 15\/ I- 1A	
Gate-Source Charge	Qgs	_	1.1	_	nC	V _{DS} = 15V, I _D = 4A	
Gate-Drain Charge	Qgd	_	1.8	_	nC		
Turn-On Delay Time	td(on)	_	1.8	_	ns		
Turn-On Rise Time	t _R	_	2.6	_	ns	V _{DS} = 15V, V _{GS} = 10V,	
Turn-Off Delay Time	tD(OFF)	_	9.5	_	ns	$R_g = 6\Omega$, $R_L = 3.75\Omega$	
Turn-Off Fall Time	t _F	_	2.1	_	ns	1	
Reverse Recovery Time	trr	_	7.0	_	ns	1 0A -11/-14 400A/	
Reverse Recovery Charge	Qrr	_	1.8	_	nC	I _F = 3A, di/dt = 100A/μs	

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

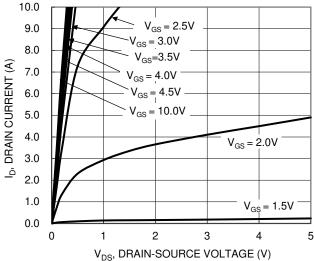
7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25$ °C.

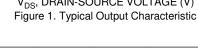
8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.









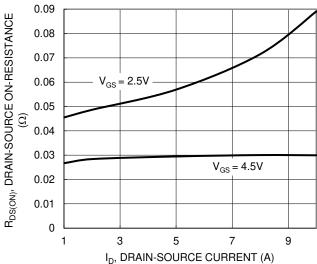


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

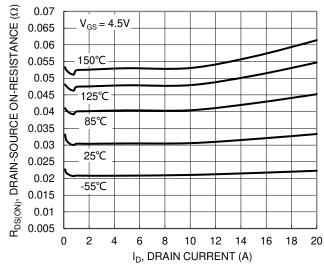


Figure 5 . Typical On-Resistance vs. Drain Current and Temperature

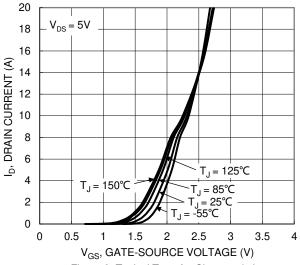


Figure 2. Typical Transfer Characteristic

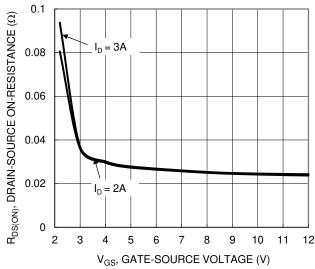


Figure 4 . Typical Transfer Characteristic

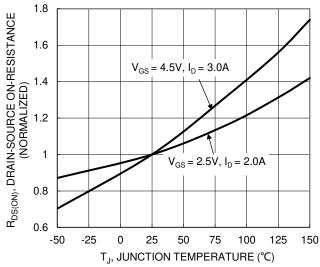


Figure 6. On-Resistance Variation with Temperature



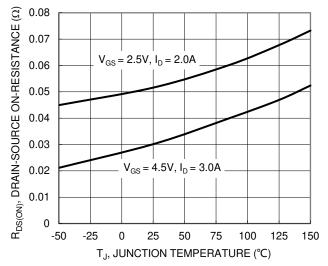
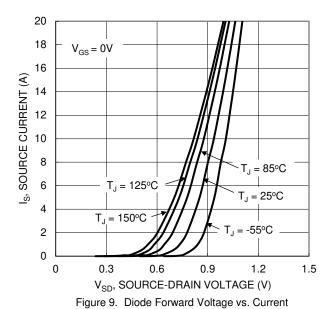
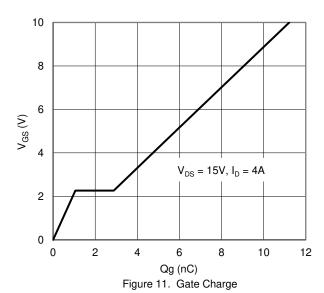


Figure 7. On-Resistance Variation with Temperature





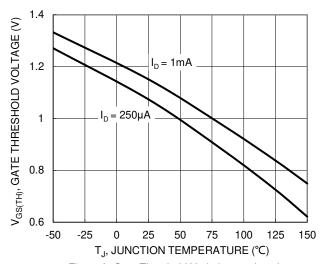
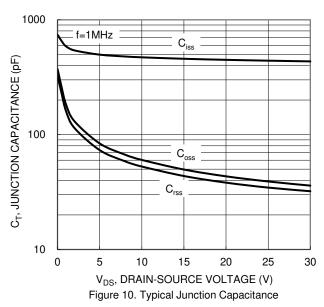
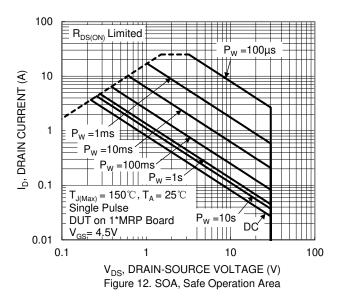


Figure 8. Gate Threshold Variation vs. Junction Temperature







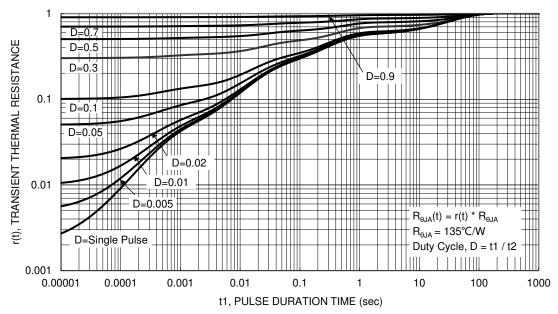


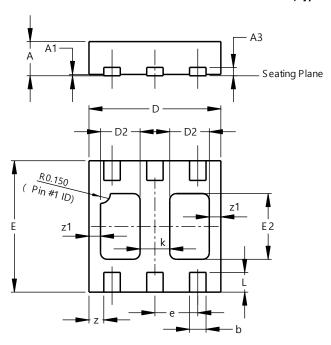
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)

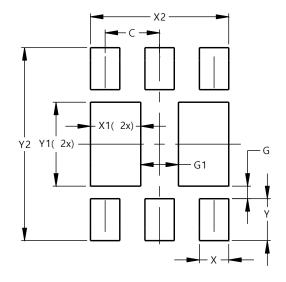


	U-DFN2020-6 Type B							
Dim	Min	Max	Тур					
Α	0.545	0.605	0.575					
A1	0.00	0.05	0.02					
A3	-	-	0.13					
b	0.20	0.30	0.25					
D	1.95	2.075	2.00					
D2	0.50	0.70	0.60					
е	-	-	0.65					
Е	1.95	2.075	2.00					
E2	0.90	1.10	1.00					
k	-	-	0.45					
L	0.25	0.35	0.30					
Z	_	-	0.225					
z1	-	-	0.175					
All Dimensions in mm								

Suggested Pad Layout

 $Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

U-DFN2020-6 (Type B)



Dimensions	Value (in mm)
С	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Υ	0.500
Y1	1.000
Y2	2.300



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